

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS7A2009PDQNR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A2009PDQNR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DQN 4	1x1x0.37	1.1

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000001	0.01258	126	0.000093	1
Precious Metals	Gold	7440-57-5	0.007948	99.98742	999874	0.73711	7371
Sub-Total			0.007949	100	1000000	0.737203	7372
Die Attach Adhesive							
Other Nonferrous Metals and Alloys	Titanium Dioxide	13463-67-7	0.000625	3.00048	30005	0.057963	580
Thermoplastics	Epoxy	85954-11-6	0.020205	96.99952	969995	1.873844	18738
Sub-Total			0.02083	100	1000000	1.931807	19318
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	0.316276	74	740000	29.331936	293319
Nickel and Its Alloys	Nickel	7440-02-0	0.035175	8.229995	82300	3.262185	32622
Thermoplastics	Epoxy	85954-11-6	0.075949	17.770005	177700	7.04363	70436
Sub-Total			0.4274	100	1000000	39.637751	396378
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.121754	95.120313	951203	11.291658	112917
Precious Metals	Gold	7440-57-5	0.000998	0.779688	7797	0.092556	926
Precious Metals	Palladium	7440-05-3	0.005248	4.1	41000	0.486708	4867
Sub-Total			0.128	100	1000000	11.870922	118709
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	0.343464	84.810114	848101	31.853394	318534
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.021059	5.20001	52000	1.953045	19530
Other Plastics and Rubber	Carbon Black	1333-86-4	0.00085	0.209887	2099	0.07883	788
Thermoplastics	Epoxy	85954-11-6	0.039607	9.779989	97800	3.673216	36732
Sub-Total			0.40498	100	1000000	37.558485	375585
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.089106	100	1000000	8.263831	82638
Sub-Total			0.089106	100	1000000	8.263831	82638
Total			1.078265			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.